

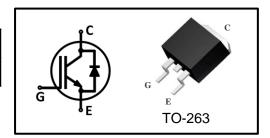
Features

- Easy parallel switching capability due to positive temperature coefficient in V_{CEsat}
- Low V_{CEsat}, fast switching
- High ruggedness, good thermal stability
- Very tight parameter distribution

Туре	Marking	Package Code
MPBC40N65EH	MP40N65EH	TO-263

Applications

- UPS
- PFC
- **■** PTC Heater
- **■** Climate Compressor



Maximum Rated Values 1

Parameter	Symbol	Value	Unit	
Collector-emitter voltage	V _{CE}	650	V	
DC collector current ²				
T _C =25°C		75		
T _C =100°C	- I _C	40		
Pulsed collector current ³	I _{Cpuls}	160		
Diode forward current ²			A	
T _C =25°C		40		
T _C =100°C	- I _F	20		
Diode pulsed current ³	I _{Fpuls}	120]	
Gate-emitter voltage	\/	±20	l v	
Transient Gate-emitter voltage (t _p ≤10us)	V_{GE}	±30	V	
Power dissipation				
T _C =25°C	В	250	W	
T _C =100°C	P _{tot}	125		
Operating junction temperature	T _j		°C	
Storage temperature	T _{stg}	-55~150		

^{1:}Reference standard: JESD-022 2: limited by Tjmax 3: Tp limited by Tjmax ;



Thermal Characteristics

Parameter	Symbol	Max	Unit
IGBT thermal resistance, junction-case	R _{thJC}	0.6	
Diode thermal resistance, junction-case	R _{thJCD}	1.8	K/W
Thermal Resistance, junction-ambient	R _{thJA}	65	

Electrical Characteristics (at Tj=25°C, unless otherwise specified) Static Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter breakdown voltage	V _{(BR)CES}	V _{GE} =0V, I _C =0.25mA	650	-	-	
Collector-emitter		V _{GE} =15V, I _C =40A T _j =25°C	ı	1.50		
saturation voltage	V _{CE(sat)}	T _j =125°C	ı	1.70	1	
		T _j =150°C	ı	1.80	1	V
	V _F	V _{GE} =0V,I _F =20A T _j =25°C	-	1.45		
Diode forward voltage		T _j =125°C	-	1.30	-	
		T _j =150°C	-	1.20	-	
G-E threshold voltage	$V_{GE(th)}$	I_{C} =0.8mA, V_{CE} = V_{GE}		5.5		
C-E leakage current	I _{CES}	V_{CE} =650V, V_{GE} =0V T_{j} =25°C	1	1	0.1	mA
		T _j =150°C	-	-	1	
G-E leakage current	I _{GES}	V _{CE} =0V, V _{GE} =20V	-	-	250	nA
Transconductance	g _{FS}	V _{CE} =20V, I _C =40A	-	35	-	S

Dynamic Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Input capacitance	C _{iss}	\/ _25\/	-	2700	-	
Output capacitance	C _{oss}	V_{CE} =25V, V_{GE} =0V,	-	120	-	pF
Reverse transfer capacitance	C _{rss}	f=1MHz	-	40	-	·
Gate charge	Q_G	V _{CC} =100V, I _C =40A, V _{GE} =15V	-	110	-	nC



IGBT Switching Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Turn-on delay time	t _{d(on)}		-	85	-	
Rise time	t _r	T _j =25°C,	-	55	-	
Turn-off delay time	t _{d(off)}	V _{CC} =400V,	-	190	1	ns
Fall time	t _f	I _C =40A, V _{GF} =0/15V,	-	40	-	
Turn-on energy	E _{on}	$R_{G}=10\Omega$,	-	0.81	-	
Turn-off energy	E _{off}	Inductive load	-	0.85	-	mJ
Total switching energy	E _{ts}		-	1.66	-	
Turn-on delay time	t _{d(on)}		-	85	-	
Rise time	t _r	T _j =150°C,	ı	70		200
Turn-off delay time	t _{d(off)}	V _{CC} =400V,	-	210	-	ns
Fall time	t _f	$I_C=40A$, $V_{GE}=0/15V$, $R_G=10\Omega$,	ı	60	1	
Turn-on energy	E _{on}		-	1.43	1	
Turn-off energy	E _{off}	Inductive load	-	1.12	-	mJ
Total switching energy	E _{ts}		-	2.55	-	

Diode Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Diode reverse recovery time	t _{rr}	T _i =25°C,	-	150	-	ns
Diode reverse recovery charge	Q _{rr}	T _j =25°C, V _R =400V, I _F =40A,	1	1.06	1	μC
Diode peak reverse recovery current	I _{rrm}	di _F /dt=640A/µs	1	15.4	1	Α
Diode reverse recovery time	t _{rr}	T _i =150°C,	1	240	1	Ns
Diode reverse recovery charge	Q _{rr}	T _j =150°C, V _R =400V, I _F =40A,	1	2.32	1	μC
Diode peak reverse recovery current	I _{rrm}	di _F /dt=640A/µs	-	21.0	-	А



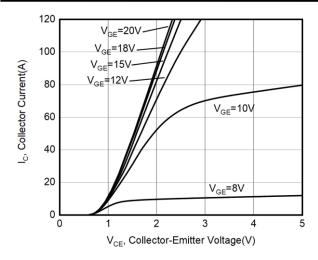


Figure 1. Typical output characteristic $(T_i = 25^{\circ}\text{C})$

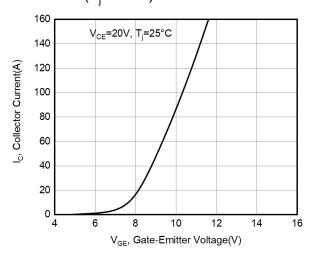


Figure 3. Typical transfer characteristic $(T_i = 25$ °C)

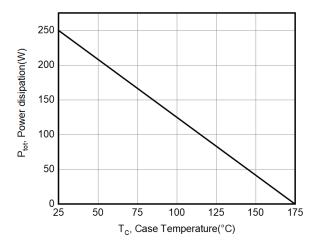


Figure 5. Power dissipation as a function of case temperature $(T_i \le 175^{\circ}C)$

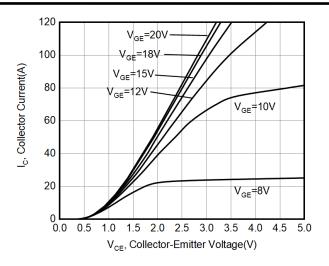


Figure 2. Typical output characteristic $(T_i = 150^{\circ}\text{C})$

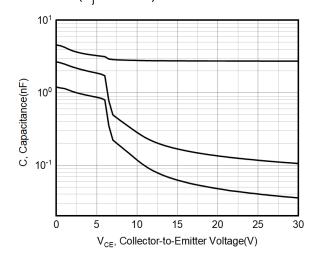


Figure 4. Capacitance characteristic $(V_{GF}=0V, f=1MHz)$

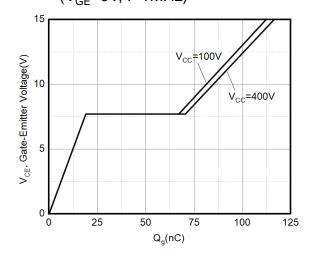


Figure 6. Typical gate charge ($I_C = 40A$)



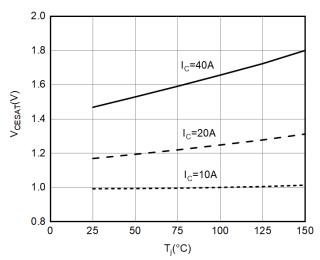


Figure 7. V_{CESAT} as a function of junction temperature (V_{GE} =15V)

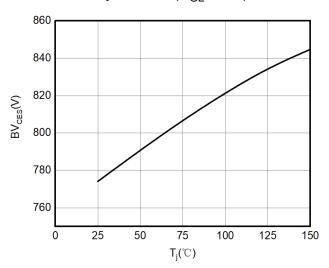


Figure 9. BV as a function of junction temperature (I_{CE} =250µA)

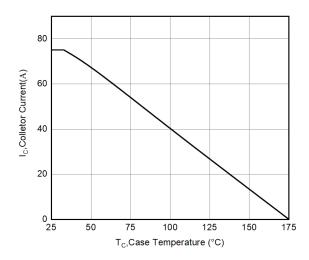


Figure 11. Collector current as a function of case temperature ($V_{GF} \ge 15 \text{V}$, $T_i \le 150 ^{\circ}\text{C}$)

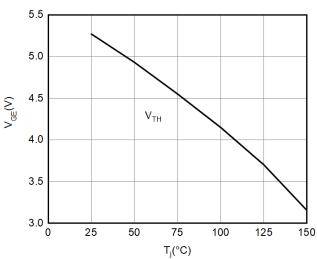


Figure 8. V_{TH} as a function of junction temperature (I_{CE} =250 μ A)

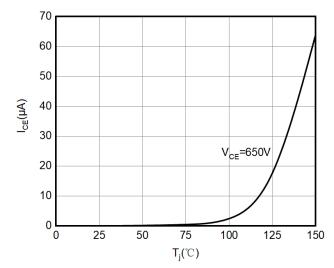


Figure 10. I_{CES} leakage current as a function of junction temperature

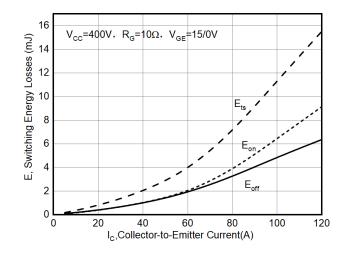


Figure 12. E_{on} , E_{off} as a function of I_{C} $(T_{i}=25^{\circ}C)$



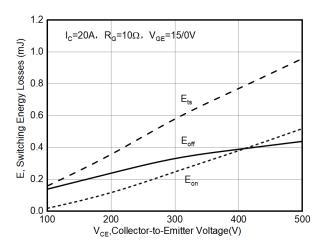


Figure 13. E_{on} , E_{off} as a function of V_{CE} $(T_i=25^{\circ}C)$

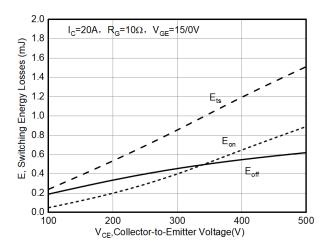


Figure 15. $E_{on,}$ E_{off} as a function of V_{CE} $(T_i=150^{\circ}C)$

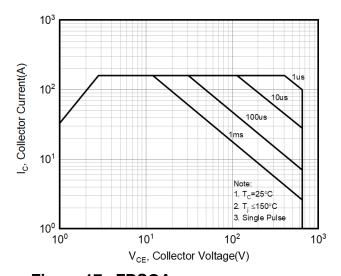


Figure 17. FBSOA

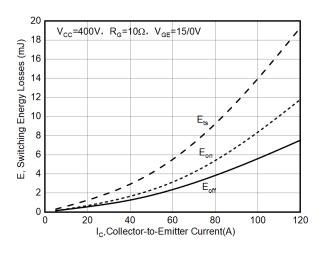


Figure 14. E_{on} , E_{off} as a function of I_{C} $(T_{i}=150^{\circ}C)$

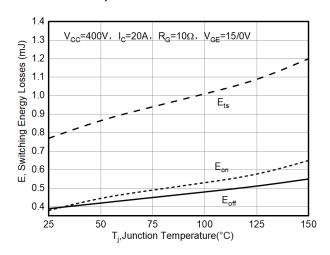
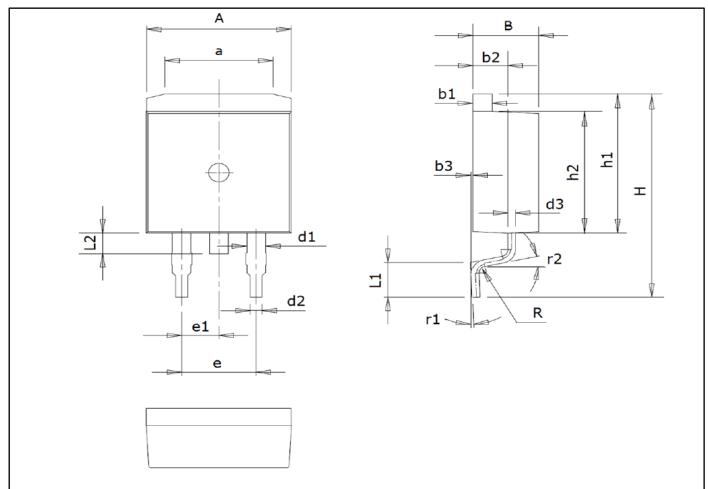


Figure 16. E_{on,} E_{off} as a function of junction temperature



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Symbol	Dimensions (mm)	Symbol	Dimensions (mm)	Symbol	Dimensions (mm)
А	9.86~10.26	d2	0.7~0.96	L1	2.0~2.6
а	7.0~7.8	d3	0.3~0.53	L2	1.3~1.8
В	4.37~4.77	е	5.08	R	0.5
b1	1.22~1.42	e1	2.54	r1	0-9°
b2	2.2~2.6	Н	14.7~15.5	r2	12°
b3	0~0.25	h1	10.3~10.7		
d1	1.17~1.47	h2	9.1~9.4		



Revision History:

Revision	Date	Subjects (major changes since last revision)
1.0	2023-02	Initial Version



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